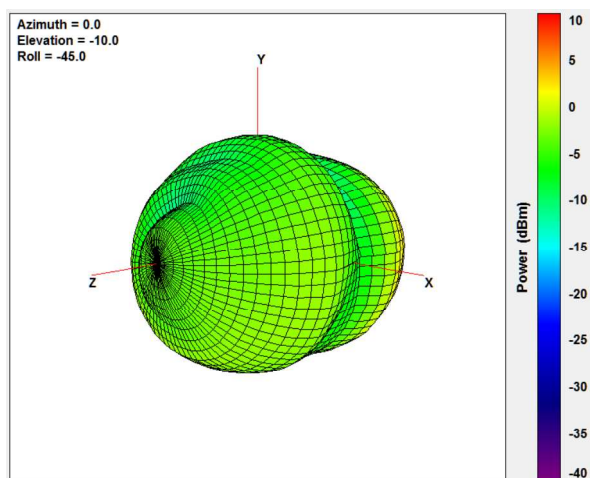
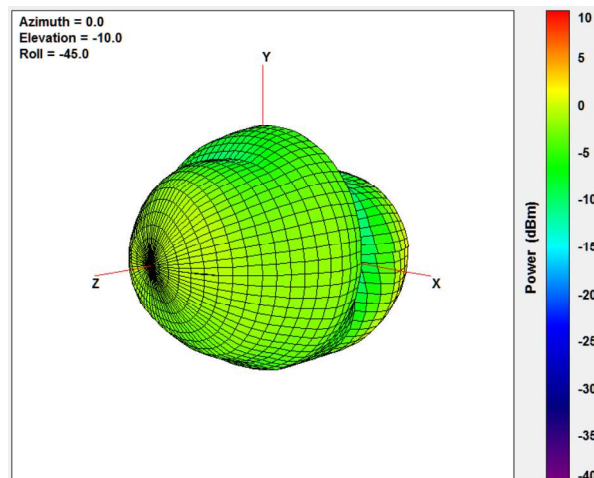
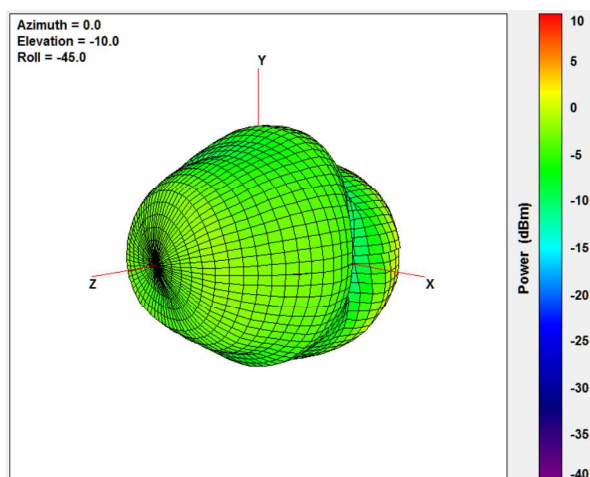




2500MHz

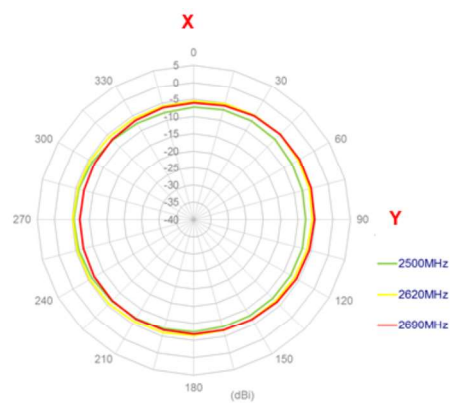


2620MHz

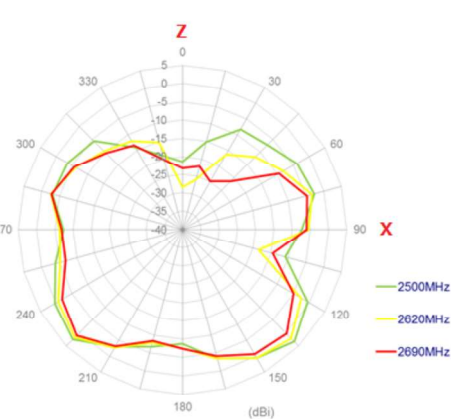


2690MHz

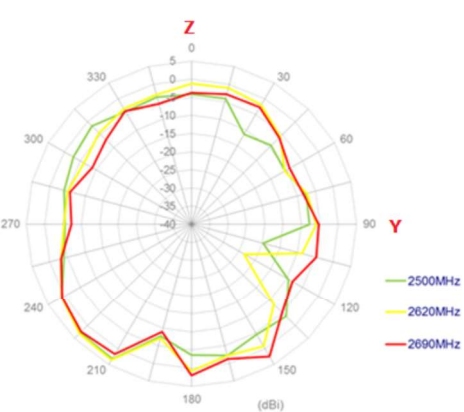
XY Plane



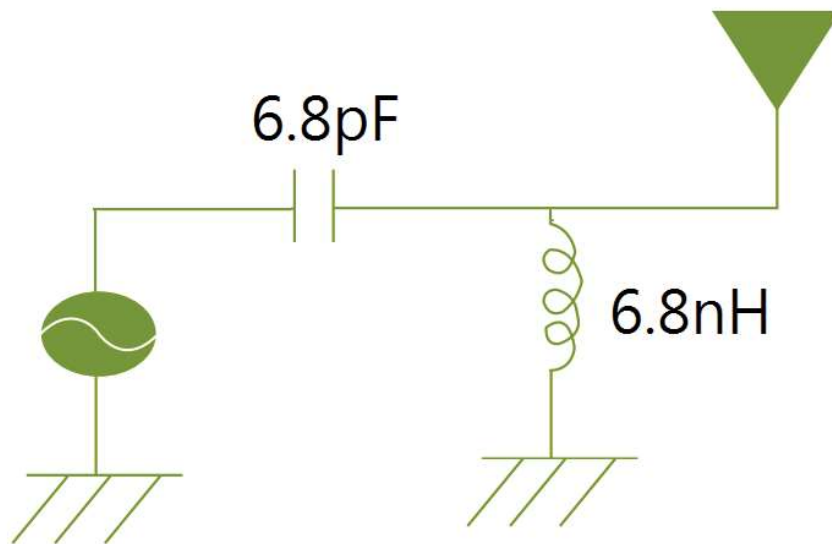
XZ Plane



YZ Plane

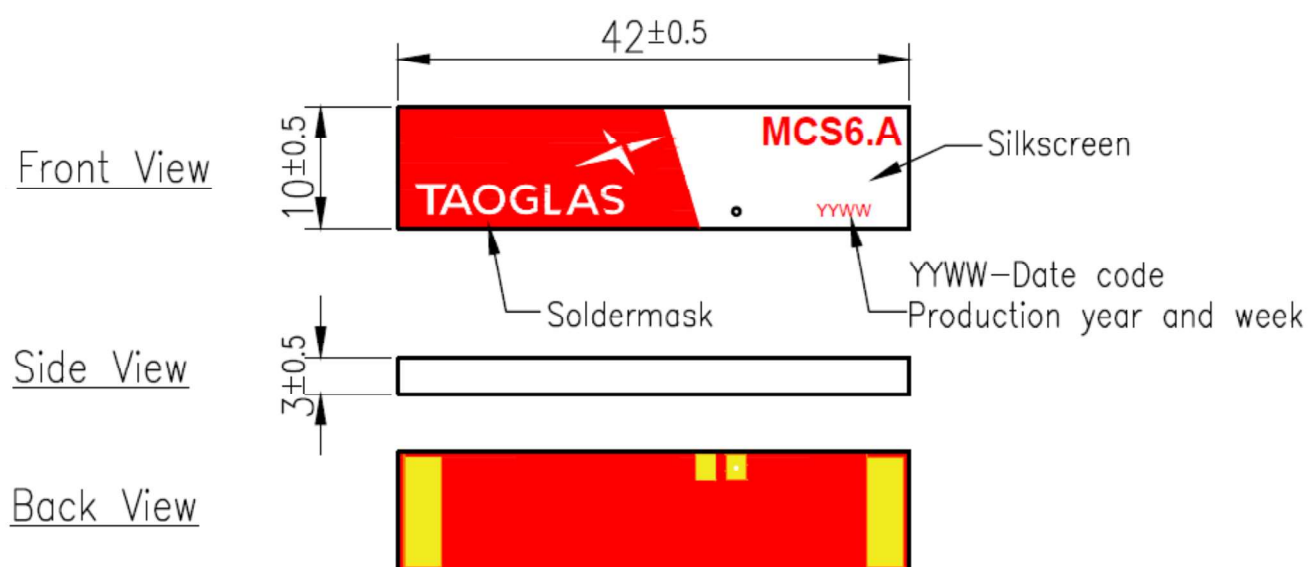


5. Matching Circuits



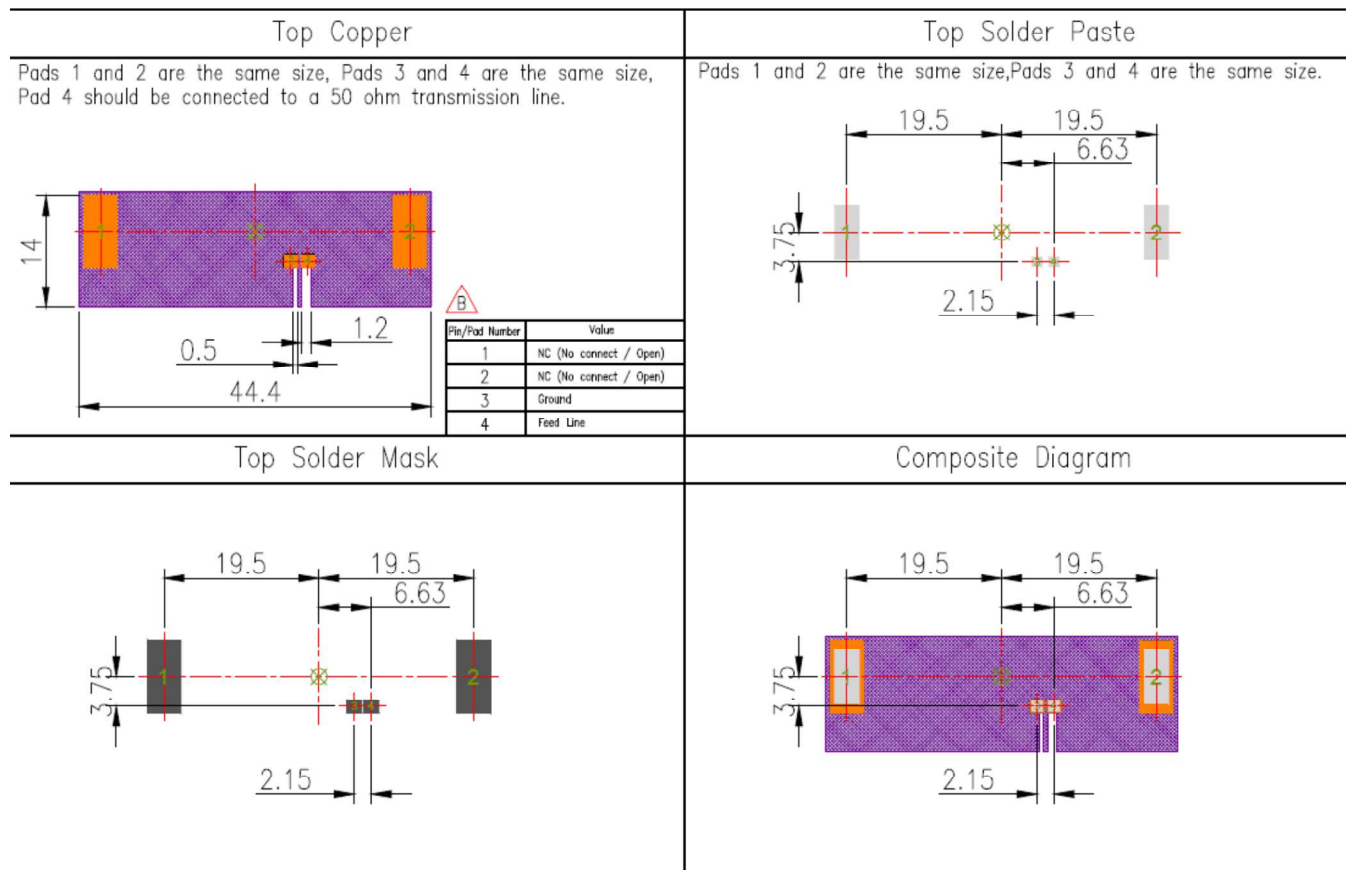
6. Mechanical Drawing

6.1 Mechanical Drawing



6.2 Footprint

FootPrint



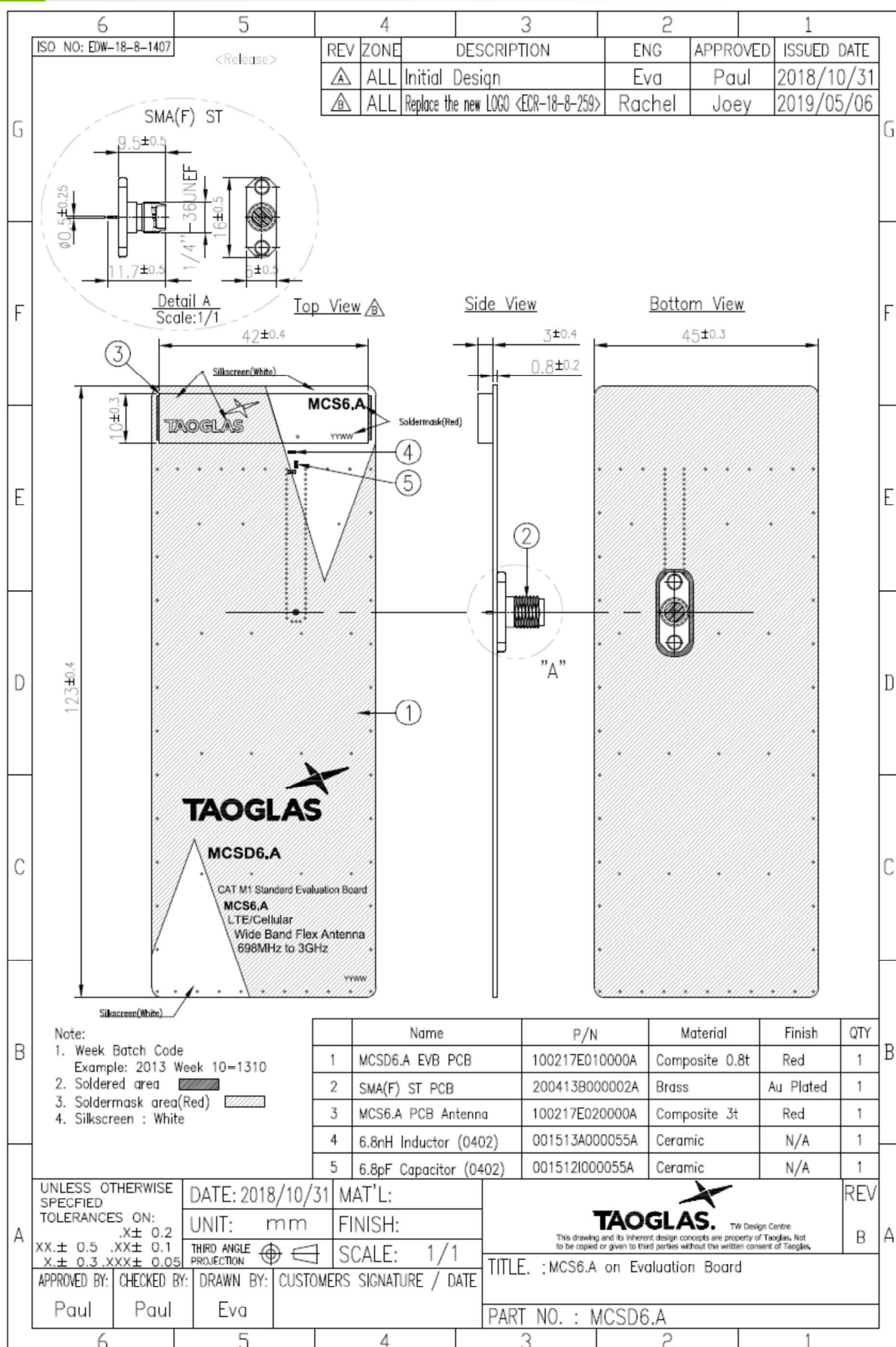
NOTE:

1. Au Plated area
2. Solder Mask area
3. Copper area
4. Paste area
5. Keepout Region area
6. Silkscreen
7. Soldermask



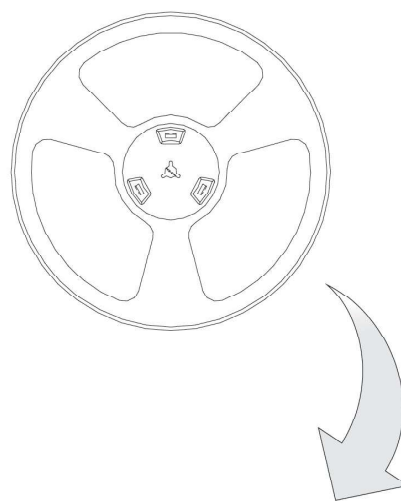
8. Ground keepout should extend through any inner PCB layers and any sides around the antenna till the board edge to minimize coupling from RF feed to ground, except the side facing system ground.
9. Any vias in pads should be either filled or tented to prevent solder from wicking away from the pad during reflow.
10. The dimension tolerances should follow standard PCB manufacturing guidelines.

6.3 Evaluation Board

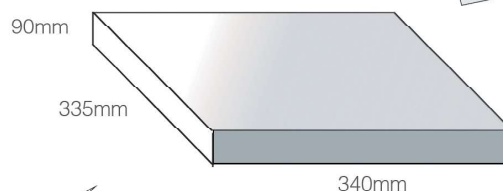


7. Packaging

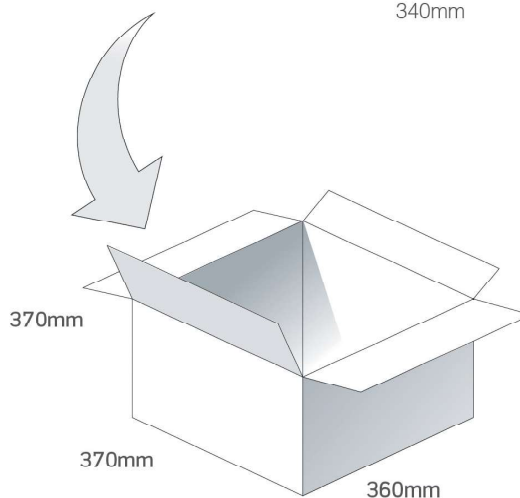
1000 pcs MCS6.A reel
Dimensions - 330*330*60mm
Weight - 2kg



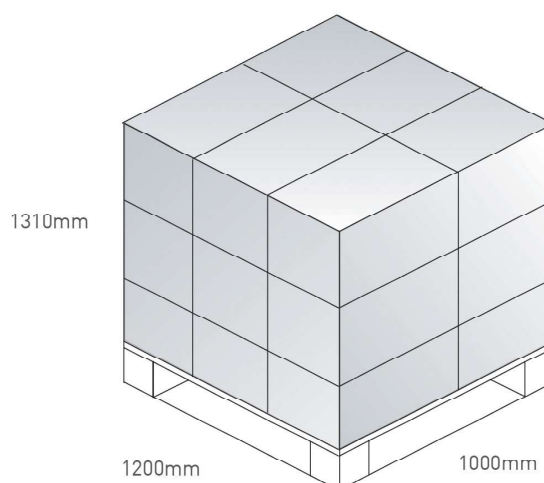
1000 pcs MCS6.A / 1 Reel in small box
Dimensions - 335*340*90mm
Weight - 2.1Kg



4 reels, 4000 pcs in one carton
Carton Dimensions - 370*360*370mm
Weight - 9.2Kg

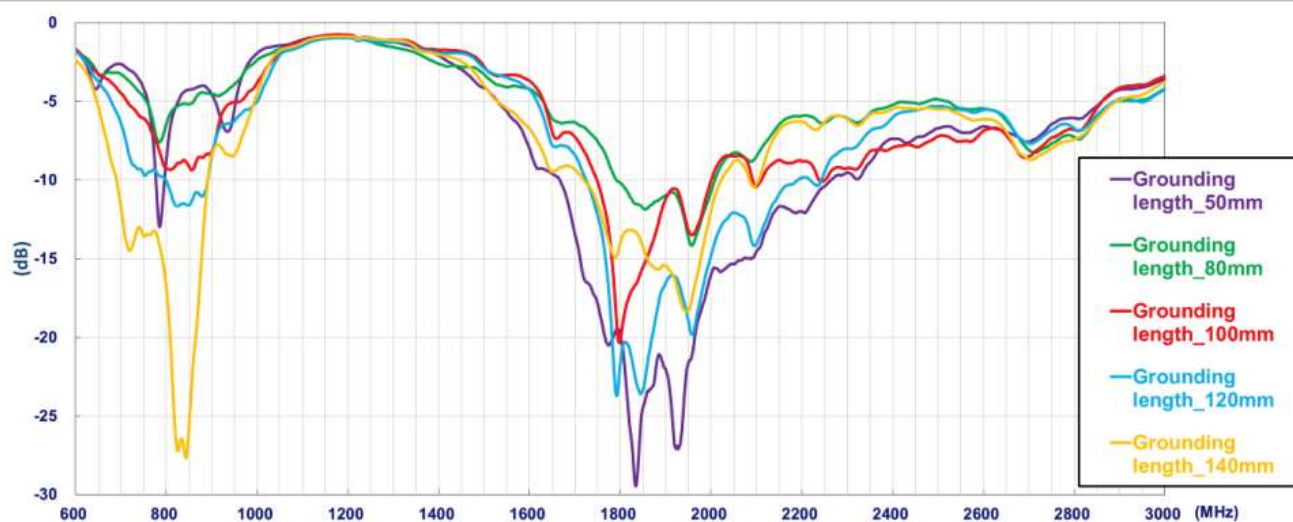


Pallet Dimensions 1200*1000*1310mm
18 Cartons per Pallet
6 Cartons per layer
3 Layers



8. Application Note

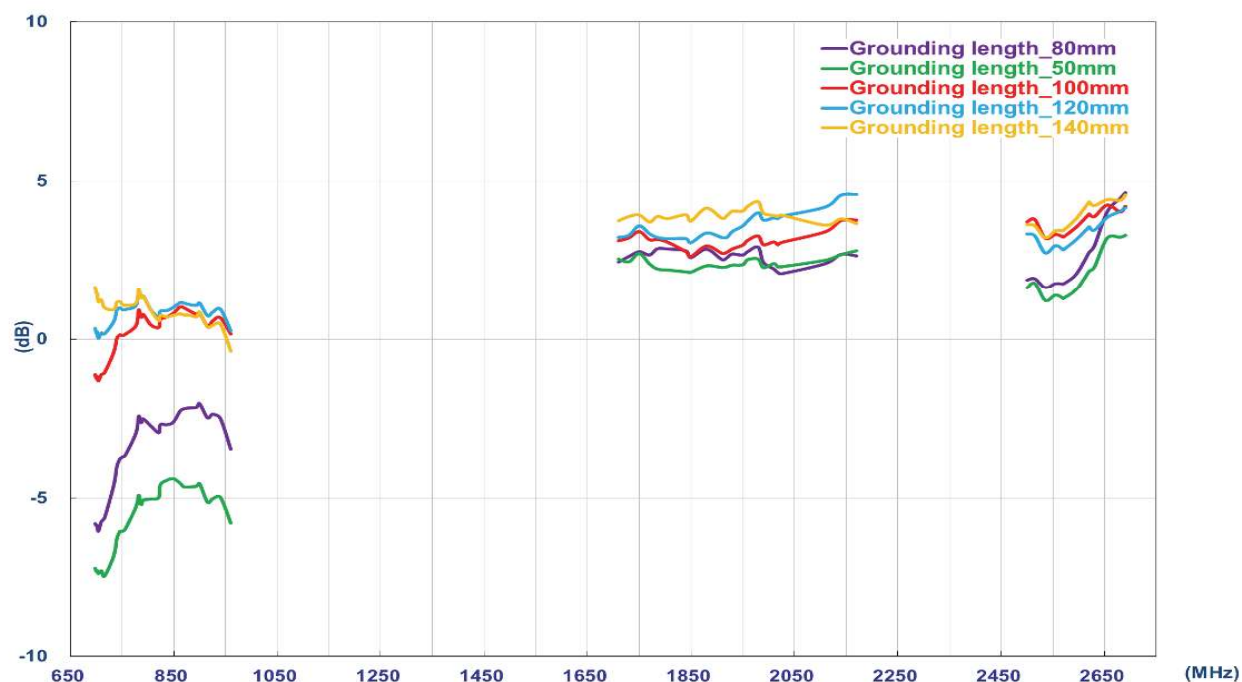
8.1 Return Loss



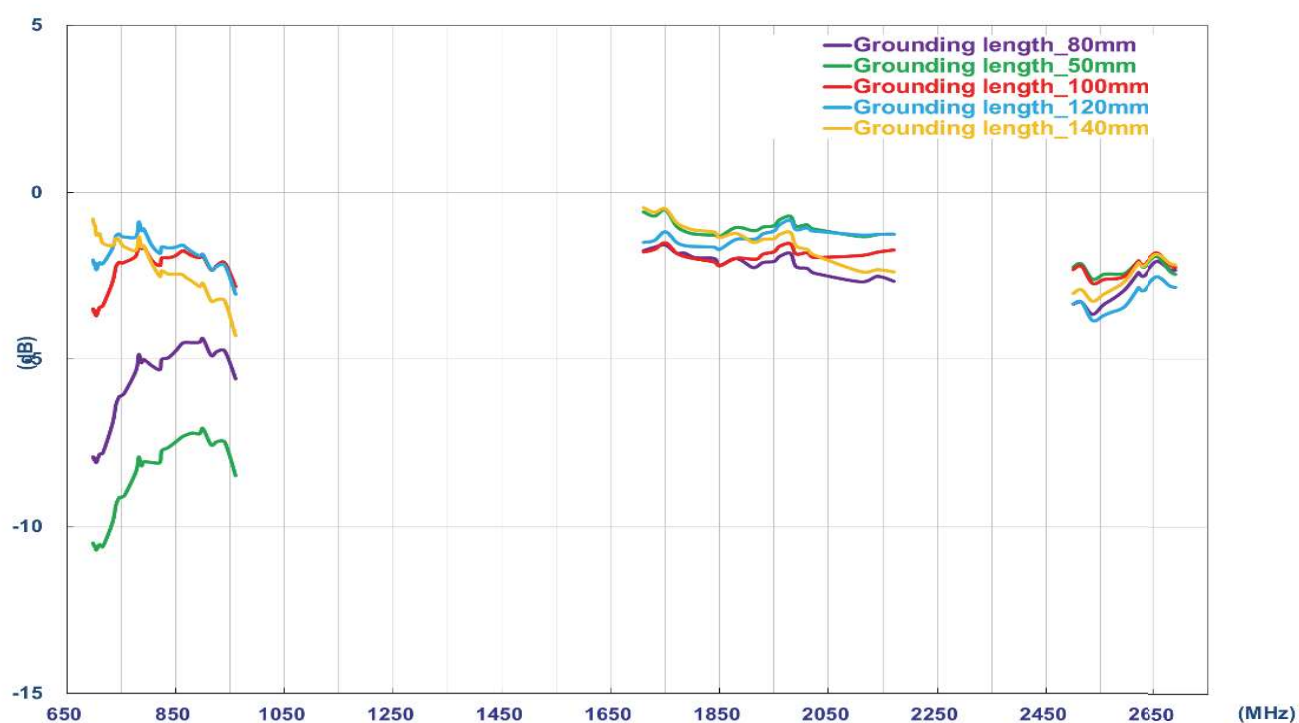
8.2 Efficiency



8.3 Peak Gain



8.4 Average Gain



Changelog for the datasheet

SPE-17-8-036 – MCS6.A

Revision: E (Current Version)

Date:	2021-09-14
Changes:	MSL, font and datasheet rev as it was listed as the "B" version.
Changes Made by:	Erik Landi

Previous Revisions

Revision: D

Date:	2019-07-25
Changes:	Template & EVB Drawing
Changes Made by:	Jack Conroy

Revision: C

Date:	2018-10-23
Changes:	Pads Amended
Changes Made by:	David Connolly

Revision: B

Date:	2017-08-08
Changes:	Drawing Updated
Changes Made by:	Andy Mahoney

Revision: A (Original First Release)

Date:	2017-08-10
Notes:	
Author:	Jack Conroy



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